ABSTRACT

The invention is a slurry for slicing a silicon ingot, containing a basic material, such as an alkali metal hydroxide, abrasive powder and water, in which the slurry contains the basic material in an amount of from 2 to 6% by mass and glycerin in an amount of from 25 to 55% by mass, based on a total mass of components of the slurry excluding the abrasive powder.